AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application to include replacing claims 10 and 11 and adding new claim 17 as follows:

LISTING OF CLAIMS:

Claim 1 (Withdrawn) A holding jig comprising:

an elastic material wherein at least the surface thereof is adhesive and conductive, and wherein an electronic part or component constituting the electronic part is holdable by the adhesive strength of the surface of the elastic material.

Claim 2 (Withdrawn) The holding jig according to claim 1, wherein the elastic material is made to be conductive by adding conductive material to the elastic material.

Claim 3 (Withdrawn) The holding jig according to claim 1, wherein the elastic material is made by conductive by installing a wiring using conductive material on the surface of the elastic material.

Claim 4 (Withdrawn) The holding jig according to claim 1, wherein the elastic material is made to be conductive by installing a wiring using conductive material inside the elastic material, the wiring being exposed on the surface of the elastic material.

Claim 5 (Previously Amended) A method of holding an electronic part or a component constituting the electronic part, comprising:

holding said electronic part or a component constituting the electronic part on a surface of an elastic material, in which at least the surface of said elastic material is adhesive and conductive, by the adhesive strength of said surface.

Claim 6 (Original) A method of manufacturing electronic parts, comprising:

holding a substrate on a surface of an elastic material, in which at least the surface of said elastic material is adhesive and conductive, by the adhesive strength of said surface; and

mounting and electrically connecting an element on said substrate while said substrate is held on the surface of said elastic material.

Claim 7 (Original) A method of manufacturing electronic parts, comprising:

holding a substrate on a surface of an elastic material, in which at least the surface of said elastic material is adhesive, by the adhesive strength of said surface; and

mounting and electrically connecting an element on said substrate while the substrate is held on the surface of the elastic material.

Claim 8 (Original) The method of manufacturing electronic parts according to claim 7, further including, applying ultrasonic waves to the bonding portion at which the electric connection is performed.

Claim 9 (Original)The method of manufacturing electronic parts according to claim 7, wherein the hardness of the elastic material is a rubber hardness degree of at least A30.

Claim 10 (Currently Amended) The method of manufacturing electronic parts according to claim 7, wherein the step of holding said substrate includes using a holding jig which comprises heat-resistant material having a heat-resistance temperature of about 250°C.

Claim 11 (Currently Amended) The method of manufacturing electronic parts according to claim 7, wherein the step of holding said substrate includes using a holding jig which includes a laminate structure of a hard plate and the elastic material.

Claim 12 (Original) The method of manufacturing electronic parts according to claim 7, wherein the elastic material comprises silicone resin.

Claim 13 (Original) The method of manufacturing electronic parts according to claim 7, wherein the mounting process includes a wire bonding process.

Claim 14 (Original) The method of manufacturing electronic parts according to claim 7, wherein the mounting process includes a bump bonding process.

Claim 15 (Previously Added) A method of manufacturing electronic parts according to claim 7, wherein the elastic material is a rubber.

Claim 16 (Previously Added) A method of manufacturing electronic parts according to claim 7, wherein the elastic material is a laminating material.

Claim 17 (New) A method of holding an electronic part or a component constituting the electronic part, comprising:

laminating an elastic material onto a holding jig; and

holding said electronic part or a component constituting the electronic part on a surface of said elastic material, in which at least the surface of said elastic material is adhesive and conductive, by the adhesive strength of said surface.